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PRIMA-SOLDER
ME8456-LV-GS002

Stress Free
Reworkable
Electrically Conductive
Epoxy Paste Adhesive

IDEAL FOR:

- Large Area Die
- Substrate and Component
- Reworkability
- Mismatched CTE's

DESCRIPTION:

ME8456-LV is a lower viscosity version of ME8456. It is a reworkable, pure silver filled, electrically and thermally conductive epoxy paste adhesive. It exhibits outstanding flexibility for bonding materials with highly mismatched CTE's (i.e., alumina to aluminum, silicon to copper).

It can be readily reworked from 80 to 100°C and is ideal for applications such as large area die attach and substrate attach because of its ability to bond materials with highly mismatched CTE's. Meets Mil-Std 883; Method 5011.4 and NASA-ESA Outgassing Requirements.

AVAILABILITY:

ME8456-LV is available in syringes for automatic needle dispense applications or in jars. Both viscosity and thixotropic index can be modified to your specific needs.

APPLICATION PROCEDURES:

- (1) Thaw for 30 minutes before opening jar.
- (2) Dispense adhesive onto clean substrate.
- (3) Pre-bake dispensed adhesive at 80°C for 30 to 60 minutes to achieve optimum bonding.
- (4) Cure according to one of the recommended schedules.

TYPICAL PROPERTIES*

Electrical Resistivity (150 °C/ 60 min)	<4x10 ⁻⁴ ohm-cm
Dielectric Strength (Volts/mil)	N/A
Glass Transition Temp.(°C)	-20
Current Carrying Capabilities	35 Amp/mm ²
Lap-Shear Strength	>1000 psi >6.9 N/mm ²
Device Push-off Strength	>2000 psi >13.8 N/mm ²
Hardness (Type)	80 (A)
Cured Density (gm/cc)	3.5
Thermal Conductivity	55 Btu-in/hr-ft ² -°F 7.9 W/m-°C
Linear Thermal Expansion Coeff. (ppm/°C)	100
Maximum Continuous Operation Temp. (°C)	150
Avg. Viscosity(0.5 rpm, 24°C) (Brookfield DV-1,spindle CP51)	50,000-90,000 cp

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

CURE SCHEDULES:

<u>Temperature</u>	<u>Time</u>
80°C	8 hr
100°C	4 hr
125°C	2 hr
150°C	1 hr

SHELF LIFE:

<u>Storage temperature</u>	<u>Shelf Life</u>
-40°C	1 yr
0°C	3 mo

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